

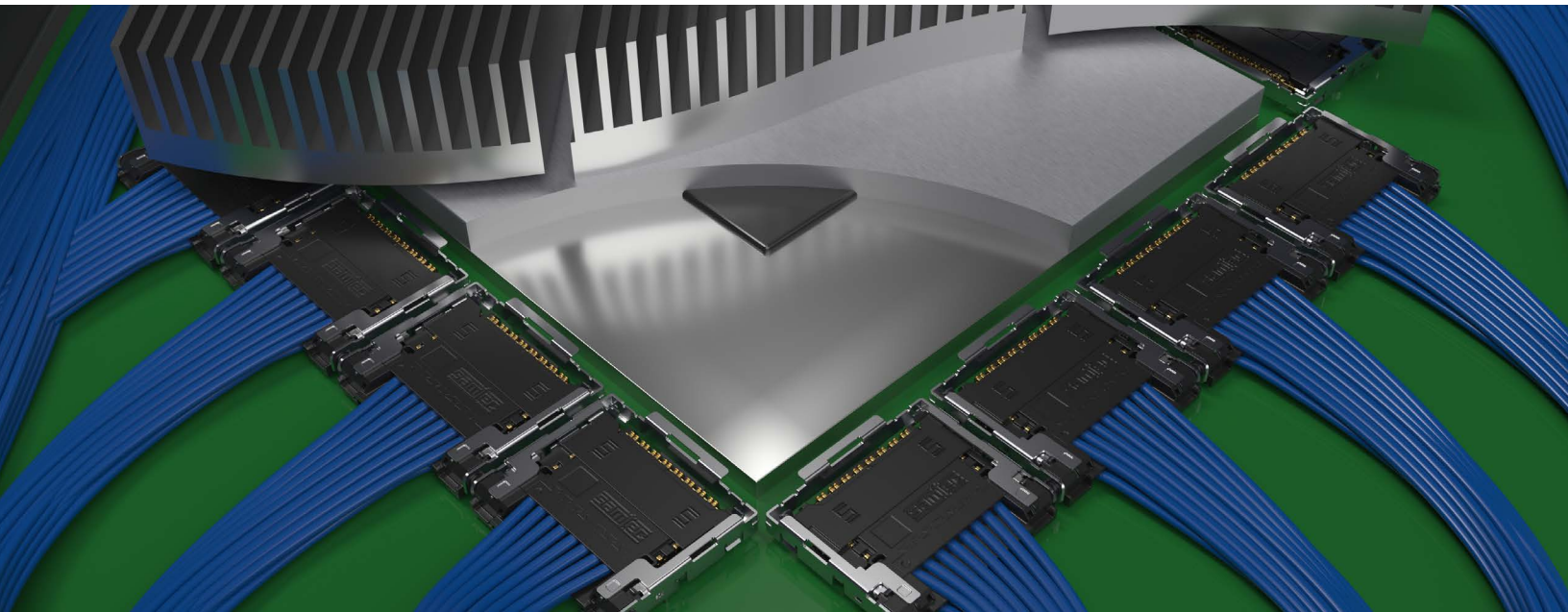


SI-FLY™

NRZ	PAM4
56 Gbps	112 Gbps

112 Gbps PAM4, LOW-PROFILE, HIGH-DENSITY CABLE SYSTEM

- Ultra low profile interconnect adjacent to the IC package
- Up to 16 pairs in an incredibly low 3.8 mm profile ideal to fit under heat sinks and other cooling hardware
- Extreme channel performance enabling 25.6 TB aggregate with a path to 51.2 TB
- 112 Gbps PAM4 per lane
- Roadmap: Co-packaged interconnect option eludes the BGA and routes signals from the silicon package through a long-reach cable, supporting 5x the signal reach of traditional PCB solutions.



~5X THE REACH, COMPARED TO TRADITIONAL PCB

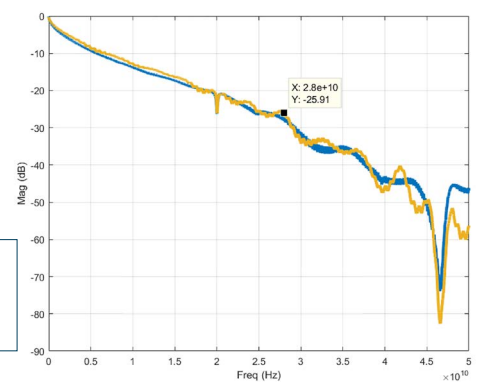


22-INCH REACH
28 dB SPEC

Conventional
PCB Topology

4.5-INCH REACH
28 dB SPEC

S-PARAMETER PLOT



For additional information visit samtec.com/si-fly

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